

UF840

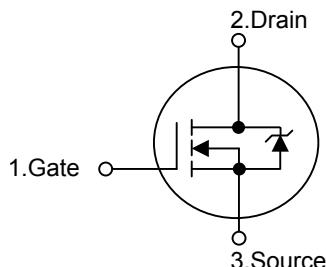
Power MOSFET

**8A, 500V, 0.85Ω, N-CHANNEL
POWER MOSFET****■ DESCRIPTION**

The N-Channel enhancement mode silicon gate power MOSFET is designed for high voltage, high speed power switching applications such as switching regulators, switching converters, solenoid, motor drivers, relay drivers.

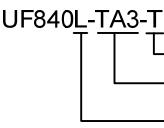
■ FEATURES

- * 8A, 500V, Low $R_{DS(ON)}=0.85\Omega$
- * Single Pulse Avalanche Energy Rated
- * Rugged - SOA is Power Dissipation Limited
- * Fast Switching Speeds
- * Linear Transfer Characteristics
- * High Input Impedance

■ SYMBOL**■ ORDERING INFORMATION**

Ordering Number			Package	Pin Assignment			Packing
Normal	Lead Free Plating	Halogen Free		1	2	3	
UF840-TA3-T	UF840L-TA3-T	UF840G-TA3-T	TO-220	G	D	S	Tube
UF840-TF1-T	UF840L-TF1-T	UF840G-TF1-T	TO-220F1	G	D	S	Tube
UF840-TF3-T	UF840L-TF3-T	UF840G-TF3-T	TO-220F	G	D	S	Tube
UF840-TQ2-R	UF840L-TQ2-R	UF840G-TQ2-R	TO-263	G	D	S	Tape Reel
UF840-TQ2-T	UF840L-TQ2-T	UF840G-TQ2-T	TO-263	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

 (1)Packing Type (2)Package Type (3)Lead Plating	(1) R: Tape Reel, T: Tube (2) TA3: TO-220, TF1: TO-220F1, TF3: TO-220F TQ2: TO-263 (3) G: Halogen Free, L: Lead Free, Blank: Pb/Sn
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■ ABSOLUTE MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$, unless Otherwise Specified.)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain to Source Voltage ($T_J = 25^\circ\text{C} \sim 125^\circ\text{C}$)		V_{DSS}	500	V
Drain to Gate Voltage ($R_{GS} = 20\text{k}\Omega$, $T_J = 25^\circ\text{C} \sim 125^\circ\text{C}$)		V_{DGR}	500	V
Gate to Source Voltage		V_{GSS}	± 30	V
Drain Current	Continuous	I_D	8.0	A
	Pulsed	I_{DM}	32	A
	TO-220	P_D	134	W
Power Dissipation ($T_C=25^\circ\text{C}$)	TO-220F/TO-220F1		44	W
	TO-263		134	W
Single Pulse Avalanche Energy		E_{AS}	510	mJ
Operating Temperature		T_{OPR}	-55 ~ +150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220	θ_{JA}	62.5	°C/W
	TO-220F/TO-220F1		62.5	°C/W
	TO-263		62.5	°C/W
Junction to Case	TO-220	θ_{JC}	0.93	°C/W
	TO-220F/TO-220F1		2.86	°C/W
	TO-263		0.93	°C/W

■ ELECTRICAL SPECIFICATIONS ($T_a = 25^\circ\text{C}$, unless Otherwise Specified.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	500			V
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$	2		4	V
On-State Drain Current (Note 1)	$I_{D(\text{ON})}$	$V_{DS} > I_{D(\text{ON})} \times R_{DS(\text{ON})\text{MAX}}$, $V_{GS} = 10\text{V}$	8			A
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = \text{Rated } BV_{DSS}$, $V_{GS} = 0\text{V}$			25	μA
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$, $V_{GS} = 0\text{V}$, $T_J = 125^\circ\text{C}$			250	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 30\text{V}$			± 100	nA
Static Drain-Source On-State Resistance (Note 1)	$R_{DS(\text{ON})}$	$I_D = 4.4\text{A}$, $V_{GS} = 10\text{V}$		0.8	0.85	Ω
Turn-On Delay Time	$t_{DLY(\text{ON})}$	$V_{DD} = 250\text{V}$, $I_D \approx 8\text{A}$, $R_G = 9.1\Omega$, $R_L = 30\Omega$ (Note 2)		15	21	ns
Turn-Off Delay Time	$t_{DLY(\text{OFF})}$			50	74	ns
Turn-On Rise Time	t_R			21	35	ns
Turn-Off Fall Time	t_F			20	30	ns
Total Gate Charge	$Q_{G(\text{TOT})}$	$V_{GS} = 10\text{V}$, $I_D = 8\text{A}$, $V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ $I_{G(\text{REF})} = 1.5\text{mA}$ (Note 3)		42	63	nC
Gate-Source Charge	Q_{GS}			7		nC
Gate-Drain Charge	Q_{GD}			22		nC
Input Capacitance	C_{ISS}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$		1225		pF
Output Capacitance	C_{OSS}			200		pF
Reverse Transfer Capacitance	C_{RSS}			85		pF

Note : 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

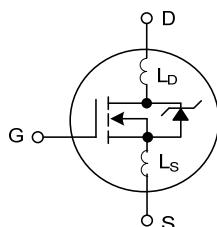
2. MOSFET Switching Times are Essentially Independent of Operating Temperature.

3. Gate Charge is Essentially Independent of Operating Temperature.

■ INTERNAL PACKAGE INDUCTANCE

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT
Drain Inductance					
Measured from the contact screw on tab to center of die	L_D		3.5		nH
Measured from the drain lead(6mm from package) to center of die			4.5		nH
Source Inductance					
Measured from the source lead(6mm from header) to source bond pad	L_S		7.5		nH

Remark: Modified MOSFET symbol showing the internal devices inductances as below.

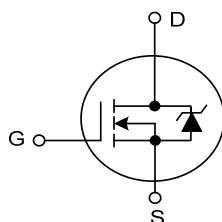


■ SOURCE TO DRAIN DIODE SPECIFICATIONS

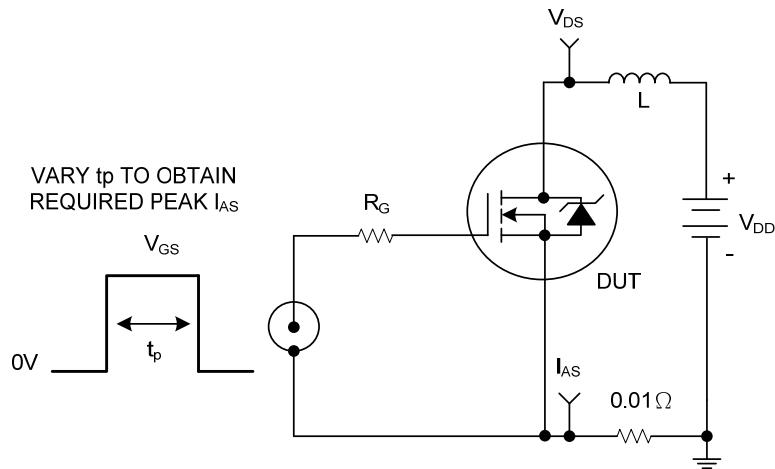
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Source to Drain Diode Voltage(Note 1)	V_{SD}	$T_J = 25^\circ C$, $I_{SD} = 8.0A$, $V_{GS} = 0V$			2	V
Continuous Source to Drain Current	I_{SD}	Note 2			8	A
Pulse Source to Drain Current	I_{SDM}				32	A
Reverse Recovery Time	t_{RR}	$T_J = 25^\circ C$, $I_{SD} = 8.0A$, $dI_{SD}/dt = 100A/\mu s$	210	475	970	ns
Reverse Recovery Charge	Q_{RR}	$T_J = 25^\circ C$, $I_{SD} = 8.0A$, $dI_{SD}/dt = 100A/\mu s$	2	4.6	8.2	μC

Notes: 1. Pulse Test: Pulse width≤300μs, Duty Cycle≤2%.

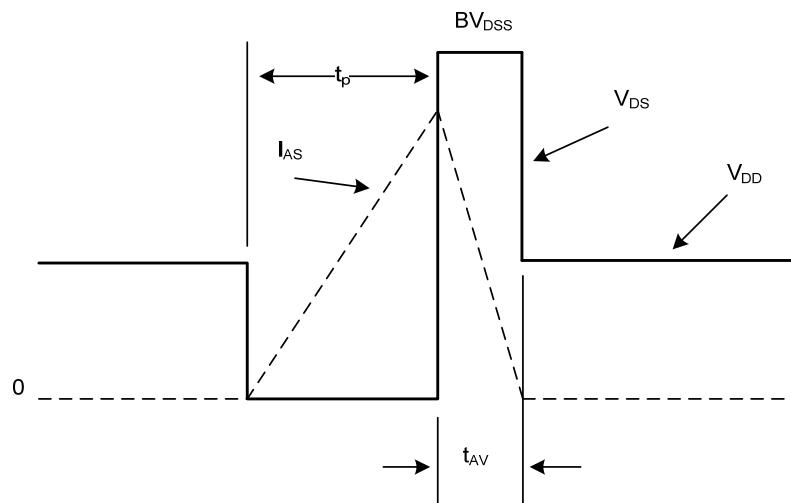
2. Modified MOSFET symbol showing the integral reverse P-N junction diode as below.



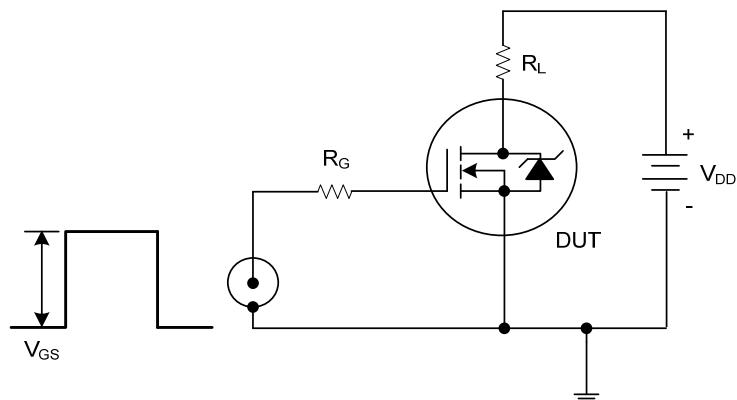
■ TEST CIRCUITS AND WAVEFORMS



UNCLAMPED ENERGY TEST CIRCUIT

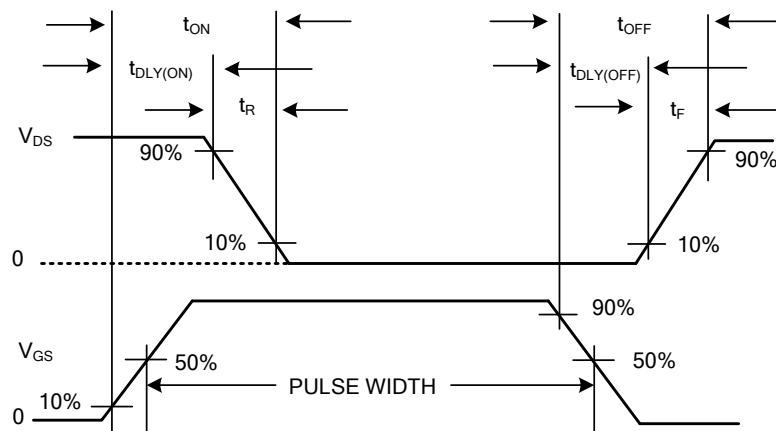


UNCLAMPED ENERGY WAVEFORMS

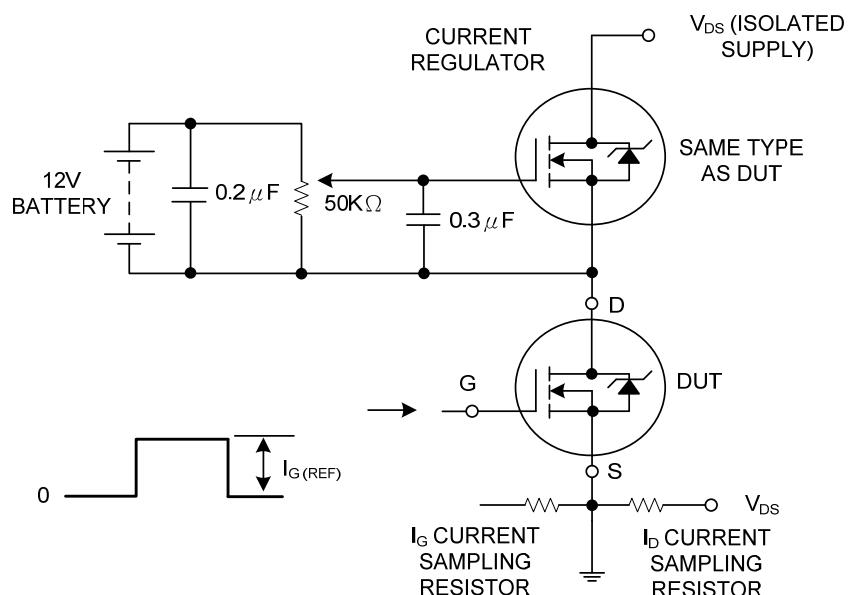


SWITCHING TIME TEST CIRCUIT

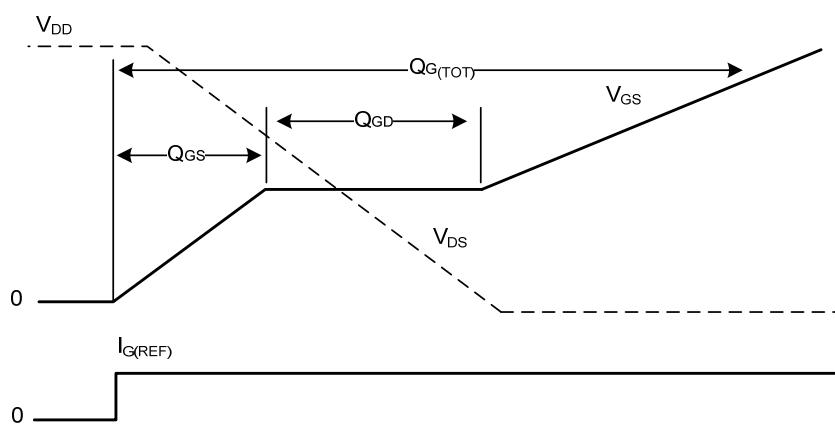
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



RESISTIVE SWITCHING WAVEFORMS

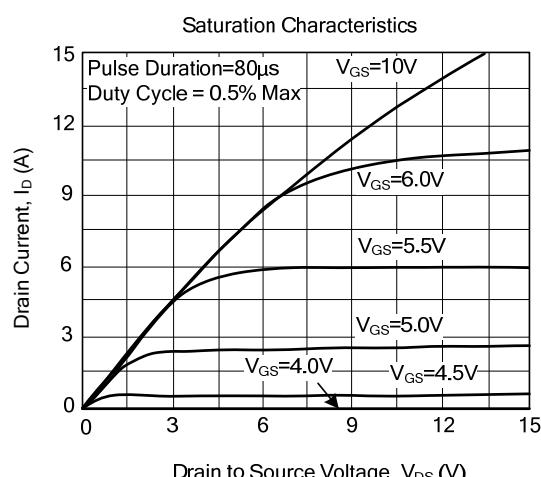
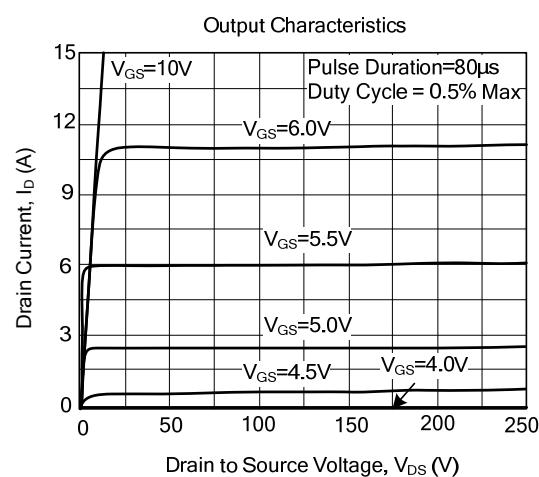
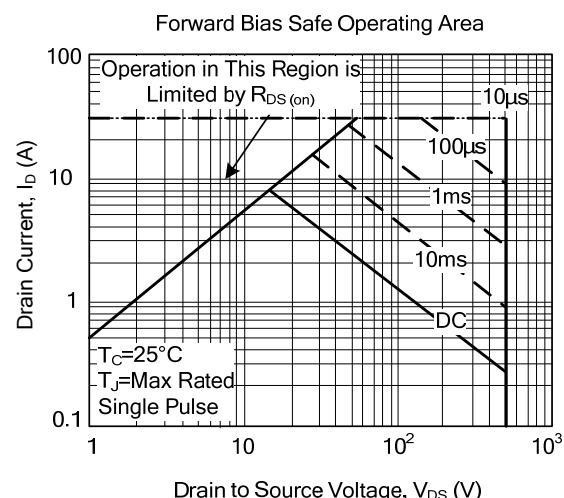
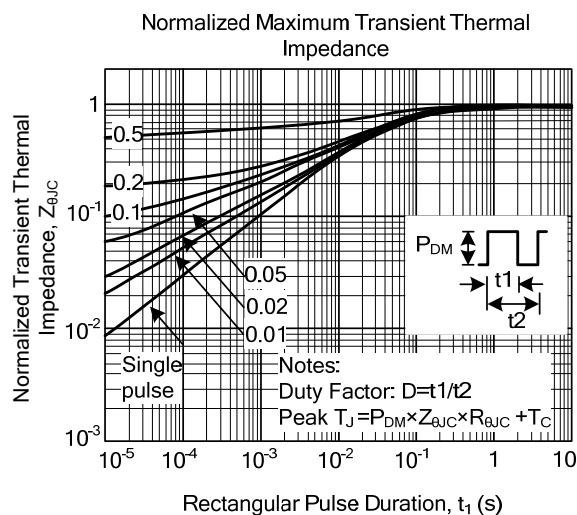
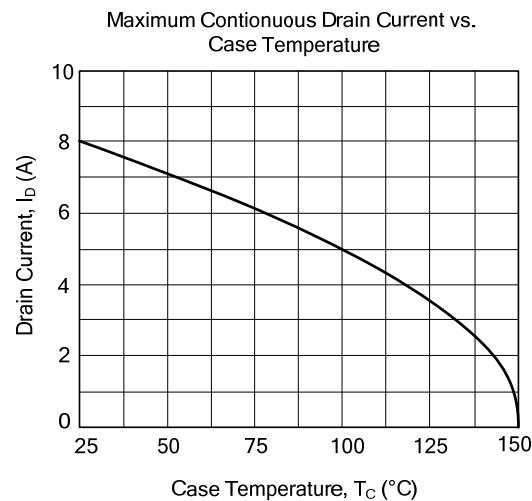
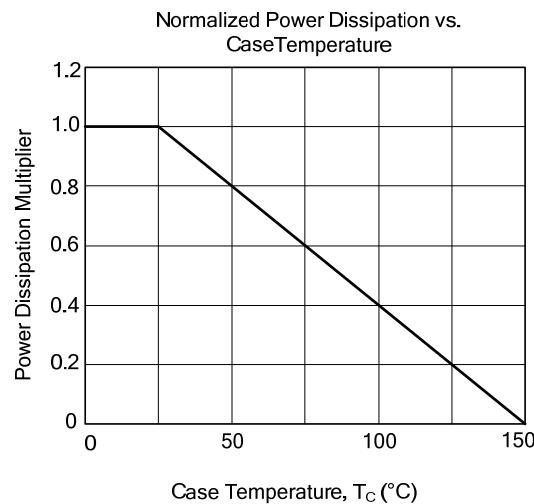


GATE CHARGE TEST CIRCUIT

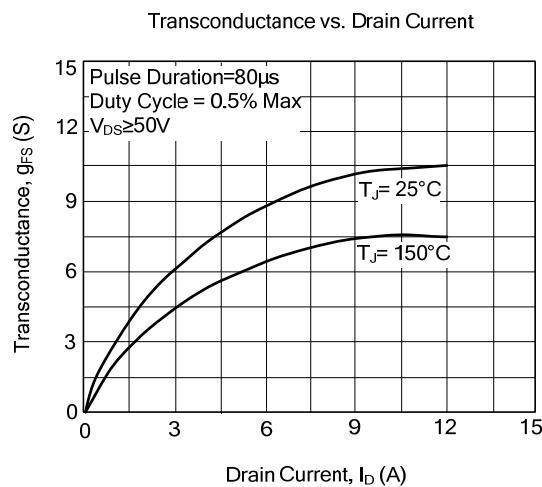
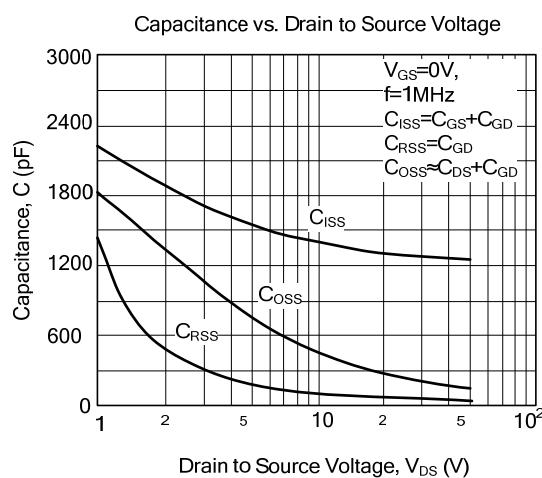
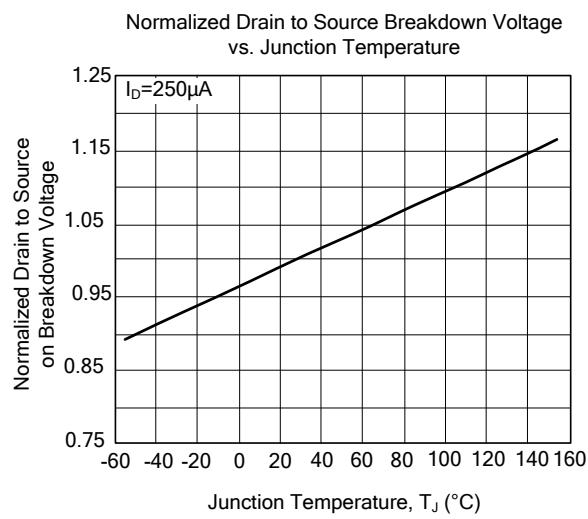
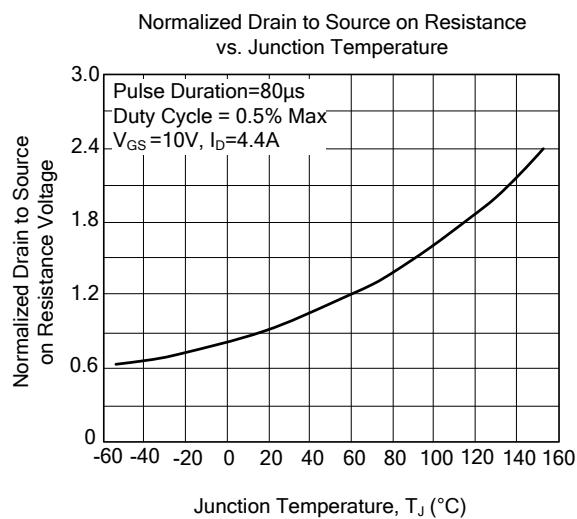
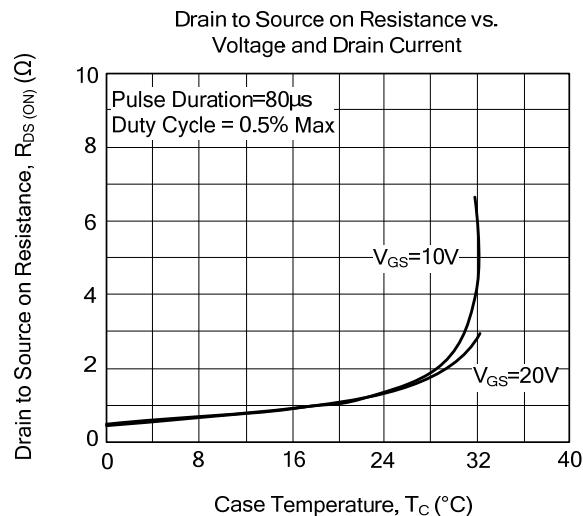
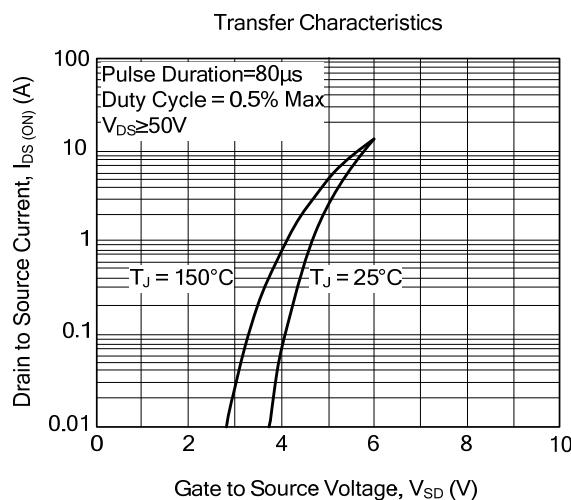


GATE CHARGE WAVEFORMS

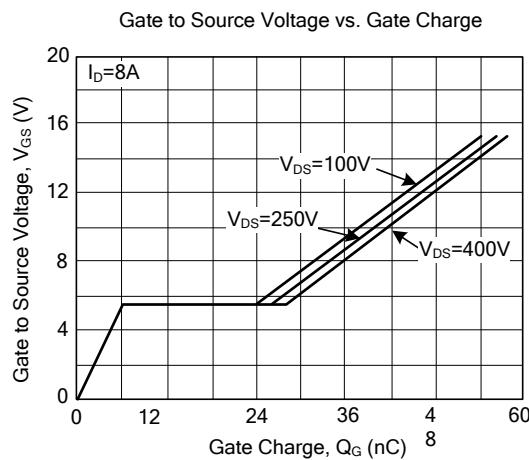
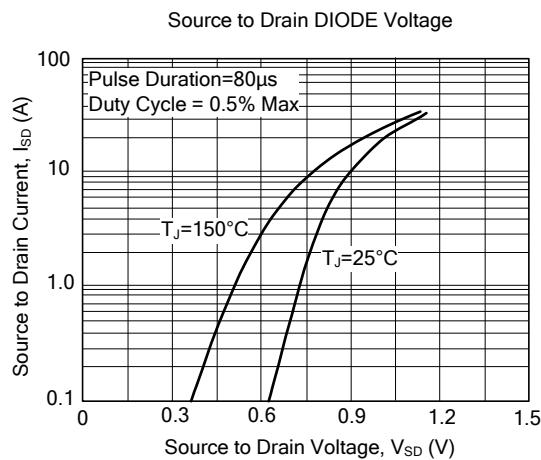
■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS(Cont.)



■ TYPICAL CHARACTERISTICS(Cont.)



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